VisionPro HSi

World Leader in Solder Paste Inspection

VisionPro HSi incorporates high-speed and high-resolution HSi positioning with sophisticated, ULTRA high speed 3-dimensional measurement technology found in ASC Internationals' popular RX sensor, to provide electronics manufacturers' with the most automatic and accurate 3-D solder paste measurement tool in its class. The HSi eliminates operator handling problems associated with other off-line measurement and inspection systems, improving repeatability and reproducibility. This makes the HSi an exceptional value for the electronics manufacturer concerned with improving production yields at high speeds.

VisionPro HSi

System Features

- Automatic calculation of 7 different characteristics, including Height, Volume, Area and Standard Deviation
- Off-line Programming (CAD or Gerber File)
- The best Gage R&R in it's class (based on the ANOVA GR&R Testing)
- Color 3-D profiles with definable color zones
- Flexible ASCII data output
- Pass/ Fail and Defect Recognition

System Includes

- 350mm x 450mm (14"x16") high speed /high-resolution positioning system
- 2.5+ GHz CPU, Windows XP/7 User Interface and SVGA monitor
- On Board SPC Charts and Data Reporting

Options

- Siemens® SPC Analysis Software
- NIST Traceable Standard
- Extended board sizes up to 560mm x 660mm (21.5" x 26")

SPC Software (Optional)

The optional Siemens® Criterion SPC software is a powerful tool that helps operators control the critical stencil printing process. Data collected by the HSi is instantly charted by the Criterion Software. Calculations crucial to understanding printing performance are reported, including:

- X and Moving Range
- X-Bar and Sigma
- X-Bar and Range
- Histograms
- P Chart, np chart, c chart and u chart
- Pareto, weighted pareto for defects and corrective actions
- Variance and standard deviation
- Skewness, kurtosis and chi-squared for goodness of fit
- Min., max. and median values
- Cr, Cp, Cpk and lower Z values

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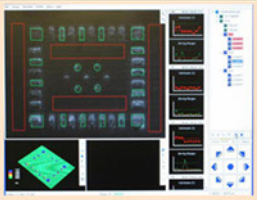
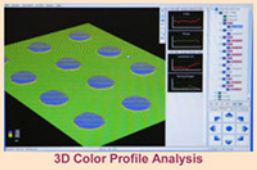


Automated Measurements

To obtain measurements on the HSi, a board is programmed once for the desired locations. After that, the user only needs to load the program, confirm the fiducial alignment, and click run. Measurements are then automatically taken at all pre-programmed locations.



3D Color Profile Analysis

The HSi allows operators to obtain 3D color profiles for fast and accurate paste analysis. Operators may use these profiles to help them determine what corrections are needed in their solder paste printing process, thereby reducing down time.

System Specifications

Maximum Object Thickness	5.1 cm (2.0")
Max Board Size **Large Configuration**	350mm x 450mm (14" x 16") 560mm x660mm(21.5" x 26")
System Computer	Windows XP/ 7 OS
Electrical Requirements	100-240 VAC, 50-60 Hz, 2 Amps
Ambient Operating Temperature	15° - 28° C (60° - 82° F)
Ambient Operating Humidity	<90% non-condensing
System Weight* (crated)	275 Kg (600 lbs)
System Weight* (un-crated)	305 Kg (673 lbs)

Sensor Specifications

Measurement Range	429 µm (16.9 mils)
Accuracy	1.0 µm (0.04mil) on calibration target
Repeatability	<10% on paste above 50um (2 mil) height minimum tolerance (+/- 50% Tolerance)
Integral Video Camera	High resolution Megapixel Camera
Field of View (FOV)	24 mm x 26 mm 0.33 seconds per FOV
Illumination	LED-based white light

H =108cm (42.5")
W=76cm (29.9")
L =138cm(54.3")

CE/UL Approved

For More Information:

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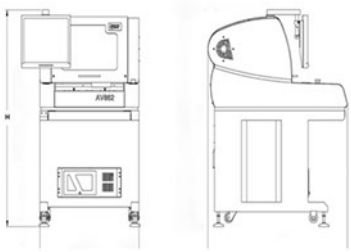

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